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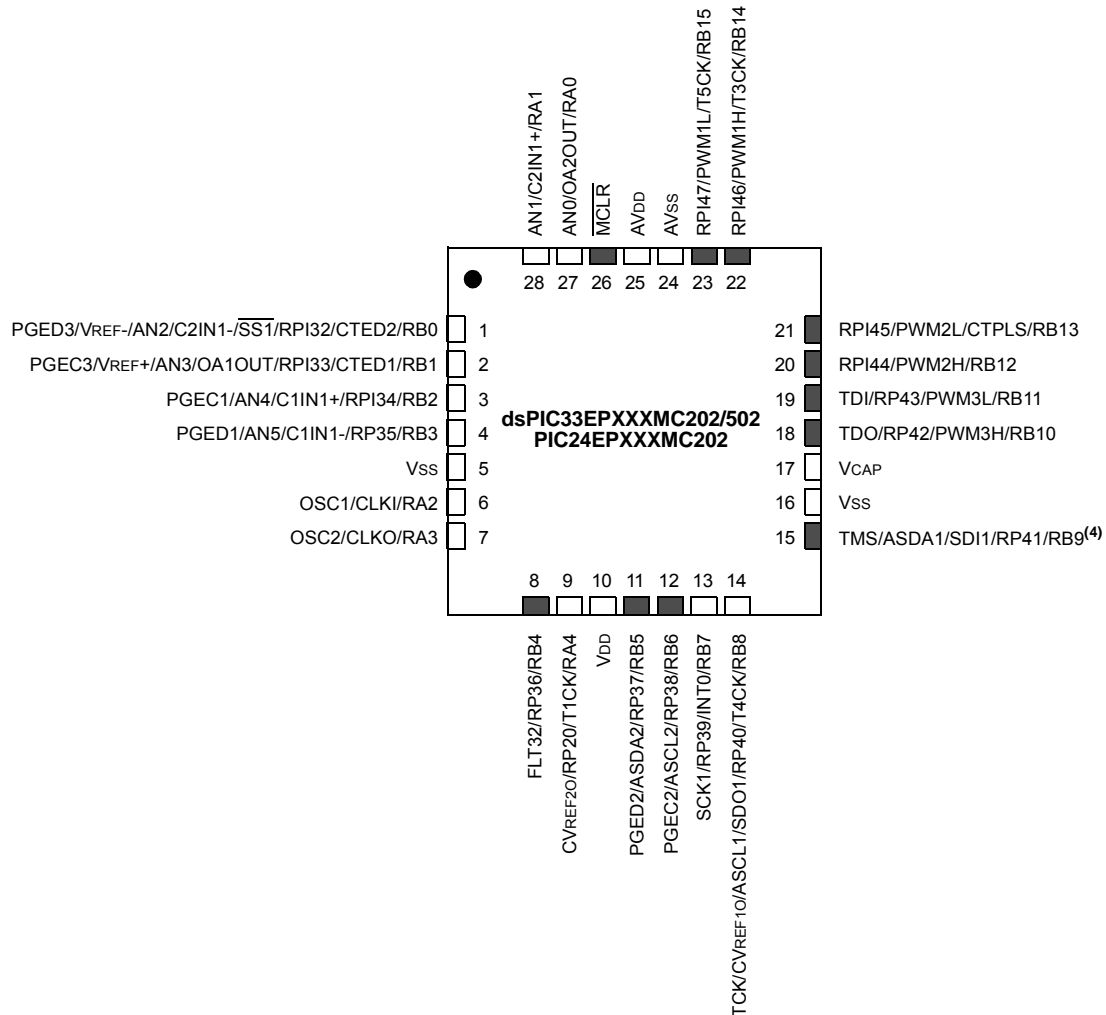
Details

Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	70 MIPS
Connectivity	I ² C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	35
Program Memory Size	128KB (43K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 9x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24ep128mc204t-i-ml

Pin Diagrams (Continued)

28-Pin QFN-S^(1,2,3)

■ = Pins are up to 5V tolerant



- Note**
- 1: The RPN/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 “Peripheral Pin Select (PPS)”** for available peripherals and for information on limitations.
 - 2: Every I/O port pin (RAX-RGx) can be used as a Change Notification pin (CNAX-CNGx). See **Section 11.0 “I/O Ports”** for more information.
 - 3: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to Vss externally.
 - 4: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name ⁽⁴⁾	Pin Type	Buffer Type	PPS	Description
U2CTS	I	ST	No	UART2 Clear-To-Send.
U2RTS	O	—	No	UART2 Ready-To-Send.
U2RX	I	ST	Yes	UART2 receive.
U2TX	O	—	Yes	UART2 transmit.
BCLK2	O	ST	No	UART2 IrDA [®] baud clock output.
SCK1	I/O	ST	No	Synchronous serial clock input/output for SPI1.
SDI1	I	ST	No	SPI1 data in.
SDO1	O	—	No	SPI1 data out.
SS1	I/O	ST	No	SPI1 slave synchronization or frame pulse I/O.
SCK2	I/O	ST	Yes	Synchronous serial clock input/output for SPI2.
SDI2	I	ST	Yes	SPI2 data in.
SDO2	O	—	Yes	SPI2 data out.
SS2	I/O	ST	Yes	SPI2 slave synchronization or frame pulse I/O.
SCL1	I/O	ST	No	Synchronous serial clock input/output for I2C1.
SDA1	I/O	ST	No	Synchronous serial data input/output for I2C1.
ASCL1	I/O	ST	No	Alternate synchronous serial clock input/output for I2C1.
ASDA1	I/O	ST	No	Alternate synchronous serial data input/output for I2C1.
SCL2	I/O	ST	No	Synchronous serial clock input/output for I2C2.
SDA2	I/O	ST	No	Synchronous serial data input/output for I2C2.
ASCL2	I/O	ST	No	Alternate synchronous serial clock input/output for I2C2.
ASDA2	I/O	ST	No	Alternate synchronous serial data input/output for I2C2.
TMS ⁽⁵⁾	I	ST	No	JTAG Test mode select pin.
TCK	I	ST	No	JTAG test clock input pin.
TDI	I	ST	No	JTAG test data input pin.
TDO	O	—	No	JTAG test data output pin.
C1RX ⁽²⁾	I	ST	Yes	ECAN1 bus receive pin.
C1TX ⁽²⁾	O	—	Yes	ECAN1 bus transmit pin.
FLT1 ⁽¹⁾ , FLT2 ⁽¹⁾	I	ST	Yes	PWM Fault Inputs 1 and 2.
FLT3 ⁽¹⁾ , FLT4 ⁽¹⁾	I	ST	No	PWM Fault Inputs 3 and 4.
FLT32 ^(1,3)	I	ST	No	PWM Fault Input 32 (Class B Fault).
DTCMP1-DTCMP3 ⁽¹⁾	I	ST	Yes	PWM Dead-Time Compensation Inputs 1 through 3.
PWM1L-PWM3L ⁽¹⁾	O	—	No	PWM Low Outputs 1 through 3.
PWM1H-PWM3H ⁽¹⁾	O	—	No	PWM High Outputs 1 through 3.
SYNCl ⁽¹⁾	I	ST	Yes	PWM Synchronization Input 1.
SYNCO ⁽¹⁾	O	—	Yes	PWM Synchronization Output 1.
INDX1 ⁽¹⁾	I	ST	Yes	Quadrature Encoder Index1 pulse input.
HOME1 ⁽¹⁾	I	ST	Yes	Quadrature Encoder Home1 pulse input.
QEA1 ⁽¹⁾	I	ST	Yes	Quadrature Encoder Phase A input in QE11 mode. Auxiliary timer external clock/gate input in Timer mode.
QEB1 ⁽¹⁾	I	ST	Yes	Quadrature Encoder Phase B input in QE11 mode. Auxiliary timer external clock/gate input in Timer mode.
CNTCMP1 ⁽¹⁾	O	—	Yes	Quadrature Encoder Compare Output 1.

Legend: CMOS = CMOS compatible input or output Analog = Analog input P = Power
ST = Schmitt Trigger input with CMOS levels O = Output I = Input
PPS = Peripheral Pin Select TTL = TTL input buffer

- Note 1:** This pin is available on dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.
- 2:** This pin is available on dsPIC33EPXXXGP/MC50X devices only.
- 3:** This is the default Fault on Reset for dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices. See **Section 16.0 “High-Speed PWM Module (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X Devices Only)”** for more information.
- 4:** Not all pins are available in all packages variants. See the **“Pin Diagrams”** section for pin availability.
- 5:** There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

3.0 CPU

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to “**CPU**” (DS70359) in the “*dsPIC33/PIC24 Family Reference Manual*”, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 “Memory Organization”** in this data sheet for device-specific register and bit information.

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X CPU has a 16-bit (data) modified Harvard architecture with an enhanced instruction set, including significant support for digital signal processing. The CPU has a 24-bit instruction word with a variable length opcode field. The Program Counter (PC) is 23 bits wide and addresses up to 4M x 24 bits of user program memory space.

An instruction prefetch mechanism helps maintain throughput and provides predictable execution. Most instructions execute in a single-cycle effective execution rate, with the exception of instructions that change the program flow, the double-word move (MOV.D) instruction, PSV accesses and the table instructions. Overhead-free program loop constructs are supported using the DO and REPEAT instructions, both of which are interruptible at any point.

3.1 Registers

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices have sixteen, 16-bit working registers in the programmer's model. Each of the working registers can act as a data, address or address offset register. The 16th working register (W15) operates as a Software Stack Pointer for interrupts and calls.

3.2 Instruction Set

The instruction set for dsPIC33EPXXXGP50X and dsPIC33EPXXXMC20X/50X devices has two classes of instructions: the MCU class of instructions and the DSP class of instructions. The instruction set for PIC24EPXXXGP/MC20X devices has the MCU class of instructions only and does not support DSP instructions. These two instruction classes are seamlessly integrated into the architecture and execute from a single execution unit. The instruction set includes many addressing modes and was designed for optimum C compiler efficiency.

3.3 Data Space Addressing

The base Data Space can be addressed as 64 Kbytes (32K words).

The Data Space includes two ranges of memory, referred to as X and Y data memory. Each memory range is accessible through its own independent Address Generation Unit (AGU). The MCU class of instructions operates solely through the X memory AGU, which accesses the entire memory map as one linear Data Space. On dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X devices, certain DSP instructions operate through the X and Y AGUs to support dual operand reads, which splits the data address space into two parts. The X and Y Data Spaces have memory locations that are device-specific, and are described further in the data memory maps in **Section 4.2 “Data Address Space”**.

The upper 32 Kbytes of the Data Space memory map can optionally be mapped into Program Space (PS) at any 32-Kbyte aligned program word boundary. The Program-to-Data Space mapping feature, known as Program Space Visibility (PSV), lets any instruction access Program Space as if it were Data Space. Moreover, the Base Data Space address is used in conjunction with a Read or Write Page register (DSRPAG or DSWPAG) to form an Extended Data Space (EDS) address. The EDS can be addressed as 8M words or 16 Mbytes. Refer to the “**Data Memory**” (DS70595) and “**Program Memory**” (DS70613) sections in the “*dsPIC33/PIC24 Family Reference Manual*” for more details on EDS, PSV and table accesses.

On the dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X devices, overhead-free circular buffers (Modulo Addressing) are supported in both X and Y address spaces. The Modulo Addressing removes the software boundary checking overhead for DSP algorithms. The X AGU Circular Addressing can be used with any of the MCU class of instructions. The X AGU also supports Bit-Reversed Addressing to greatly simplify input or output data re-ordering for radix-2 FFT algorithms. PIC24EPXXXGP/MC20X devices do not support Modulo and Bit-Reversed Addressing.

3.4 Addressing Modes

The CPU supports these addressing modes:

- Inherent (no operand)
- Relative
- Literal
- Memory Direct
- Register Direct
- Register Indirect

Each instruction is associated with a predefined addressing mode group, depending upon its functional requirements. As many as six addressing modes are supported for each instruction.

TABLE 4-37: PMD REGISTER MAP FOR PIC24EPXXXGP20X DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
PMD1	0760	T5MD	T4MD	T3MD	T2MD	T1MD	—	—	—	I2C1MD	U2MD	U1MD	SPI2MD	SPI1MD	—	—	AD1MD	0000
PMD2	0762	—	—	—	—	IC4MD	IC3MD	IC2MD	IC1MD	—	—	—	—	OC4MD	OC3MD	OC2MD	OC1MD	0000
PMD3	0764	—	—	—	—	—	CMPMD	—	—	CRCMD	—	—	—	—	—	I2C2MD	—	0000
PMD4	0766	—	—	—	—	—	—	—	—	—	—	—	—	REFOMD	CTMUMD	—	—	0000
PMD6	076A	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
PMD7	076C	—	—	—	—	—	—	—	—	—	—	—	DMA0MD	PTGMD	—	—	—	0000
													DMA1MD					
													DMA2MD					
													DMA3MD					

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-38: PMD REGISTER MAP FOR PIC24EPXXXMC20X DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
PMD1	0760	T5MD	T4MD	T3MD	T2MD	T1MD	QE11MD	PWMMD	—	I2C1MD	U2MD	U1MD	SPI2MD	SPI1MD	—	—	AD1MD	0000
PMD2	0762	—	—	—	—	IC4MD	IC3MD	IC2MD	IC1MD	—	—	—	—	OC4MD	OC3MD	OC2MD	OC1MD	0000
PMD3	0764	—	—	—	—	—	CMPMD	—	—	CRCMD	—	—	—	—	—	I2C2MD	—	0000
PMD4	0766	—	—	—	—	—	—	—	—	—	—	—	—	REFOMD	CTMUMD	—	—	0000
PMD6	076A	—	—	—	—	—	PWM3MD	PWM2MD	PWM1MD	—	—	—	—	—	—	—	—	0000
PMD7	076C	—	—	—	—	—	—	—	—	—	—	—	DMA0MD	PTGMD	—	—	—	0000
													DMA1MD					
													DMA2MD					
													DMA3MD					

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

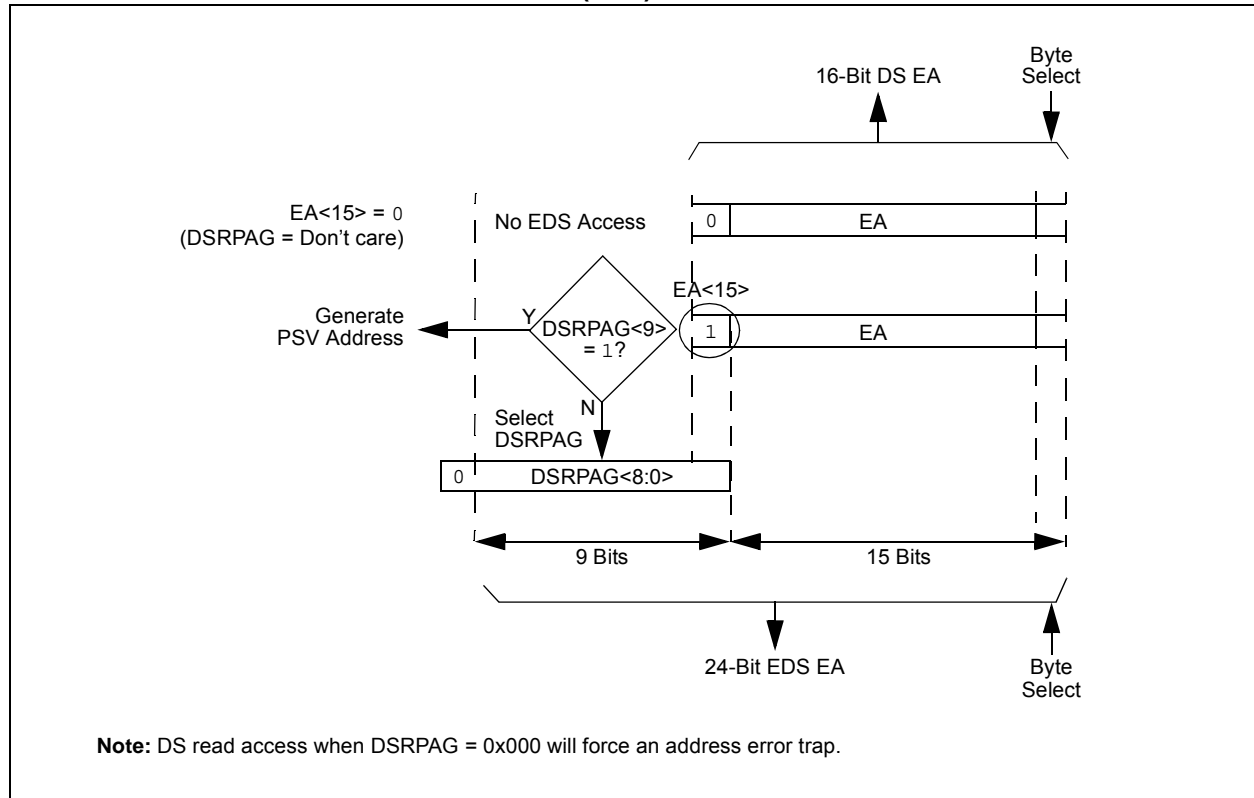
4.4.1 PAGED MEMORY SCHEME

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X architecture extends the available Data Space through a paging scheme, which allows the available Data Space to be accessed using MOV instructions in a linear fashion for pre-modified and post-modified Effective Addresses (EA). The upper half of the base Data Space address is used in conjunction with the Data Space Page registers, the 10-bit Read Page register (DSRPAG) or the 9-bit Write Page register (DSWPAG), to form an Extended Data Space (EDS)

address or Program Space Visibility (PSV) address. The Data Space Page registers are located in the SFR space.

Construction of the EDS address is shown in Example 4-1. When DSRPAG<9> = 0 and the base address bit, EA<15> = 1, the DSRPAG<8:0> bits are concatenated onto EA<14:0> to form the 24-bit EDS read address. Similarly, when base address bit, EA<15> = 1, DSWPAG<8:0> are concatenated onto EA<14:0> to form the 24-bit EDS write address.

EXAMPLE 4-1: EXTENDED DATA SPACE (EDS) READ ADDRESS GENERATION



4.5.3 MOVE AND ACCUMULATOR INSTRUCTIONS

Move instructions, which apply to dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices, and the DSP accumulator class of instructions, which apply to the dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X devices, provide a greater degree of addressing flexibility than other instructions. In addition to the addressing modes supported by most MCU instructions, move and accumulator instructions also support Register Indirect with Register Offset Addressing mode, also referred to as Register Indexed mode.

Note: For the <code>MOV</code> instructions, the addressing mode specified in the instruction can differ for the source and destination EA. However, the 4-bit <code>Wb</code> (Register Offset) field is shared by both source and destination (but typically only used by one).
--

In summary, the following addressing modes are supported by move and accumulator instructions:

- Register Direct
- Register Indirect
- Register Indirect Post-modified
- Register Indirect Pre-modified
- Register Indirect with Register Offset (Indexed)
- Register Indirect with Literal Offset
- 8-Bit Literal
- 16-Bit Literal

Note: Not all instructions support all the addressing modes given above. Individual instructions may support different subsets of these addressing modes.
--

4.5.4 MAC INSTRUCTIONS (dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X DEVICES ONLY)

The dual source operand DSP instructions (`CLR`, `ED`, `EDAC`, `MAC`, `MPY`, `MPY.N`, `MOVSAC` and `MSC`), also referred to as `MAC` instructions, use a simplified set of addressing modes to allow the user application to effectively manipulate the Data Pointers through register indirect tables.

The Two-Source Operand Prefetch registers must be members of the set: {W8, W9, W10, W11}. For data reads, W8 and W9 are always directed to the X RAGU, and W10 and W11 are always directed to the Y AGU. The Effective Addresses generated (before and after modification) must therefore, be valid addresses within X Data Space for W8 and W9, and Y Data Space for W10 and W11.

Note: Register Indirect with Register Offset Addressing mode is available only for W9 (in X space) and W11 (in Y space).

In summary, the following addressing modes are supported by the `MAC` class of instructions:

- Register Indirect
- Register Indirect Post-Modified by 2
- Register Indirect Post-Modified by 4
- Register Indirect Post-Modified by 6
- Register Indirect with Register Offset (Indexed)

4.5.5 OTHER INSTRUCTIONS

Besides the addressing modes outlined previously, some instructions use literal constants of various sizes. For example, `BRA` (branch) instructions use 16-bit signed literals to specify the branch destination directly, whereas the `DISI` instruction uses a 14-bit unsigned literal field. In some instructions, such as `ULNK`, the source of an operand or result is implied by the opcode itself. Certain operations, such as a `NOF`, do not have any operands.

REGISTER 6-1: RCON: RESET CONTROL REGISTER⁽¹⁾

R/W-0	R/W-0	U-0	U-0	R/W-0	U-0	R/W-0	R/W-0
TRAPR	IOPUWR	—	—	VREGSF	—	CM	VREGS
bit 15						bit 8	

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-1	R/W-1
EXTR	SWR	SWDTEN ⁽²⁾	WDTO	SLEEP	IDLE	BOR	POR
bit 7						bit 0	

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

- bit 15 **TRAPR:** Trap Reset Flag bit
1 = A Trap Conflict Reset has occurred
0 = A Trap Conflict Reset has not occurred
- bit 14 **IOPUWR:** Illegal Opcode or Uninitialized W Access Reset Flag bit
1 = An illegal opcode detection, an illegal address mode or Uninitialized W register used as an Address Pointer caused a Reset
0 = An illegal opcode or Uninitialized W register Reset has not occurred
- bit 13-12 **Unimplemented:** Read as '0'
- bit 11 **VREGSF:** Flash Voltage Regulator Standby During Sleep bit
1 = Flash voltage regulator is active during Sleep
0 = Flash voltage regulator goes into Standby mode during Sleep
- bit 10 **Unimplemented:** Read as '0'
- bit 9 **CM:** Configuration Mismatch Flag bit
1 = A Configuration Mismatch Reset has occurred.
0 = A Configuration Mismatch Reset has not occurred
- bit 8 **VREGS:** Voltage Regulator Standby During Sleep bit
1 = Voltage regulator is active during Sleep
0 = Voltage regulator goes into Standby mode during Sleep
- bit 7 **EXTR:** External Reset ($\overline{\text{MCLR}}$) Pin bit
1 = A Master Clear (pin) Reset has occurred
0 = A Master Clear (pin) Reset has not occurred
- bit 6 **SWR:** Software RESET (Instruction) Flag bit
1 = A RESET instruction has been executed
0 = A RESET instruction has not been executed
- bit 5 **SWDTEN:** Software Enable/Disable of WDT bit⁽²⁾
1 = WDT is enabled
0 = WDT is disabled
- bit 4 **WDTO:** Watchdog Timer Time-out Flag bit
1 = WDT time-out has occurred
0 = WDT time-out has not occurred

Note 1: All of the Reset status bits can be set or cleared in software. Setting one of these bits in software does not cause a device Reset.

2: If the FWDTEN Configuration bit is '1' (unprogrammed), the WDT is always enabled, regardless of the SWDTEN bit setting.

TABLE 9-1: CONFIGURATION BIT VALUES FOR CLOCK SELECTION

Oscillator Mode	Oscillator Source	POSCMD<1:0>	FNOSC<2:0>	See Notes
Fast RC Oscillator with Divide-by-N (FRCDIVN)	Internal	xx	111	1, 2
Fast RC Oscillator with Divide-by-16 (FRCDIV16)	Internal	xx	110	1
Low-Power RC Oscillator (LPRC)	Internal	xx	101	1
Primary Oscillator (HS) with PLL (HSPLL)	Primary	10	011	
Primary Oscillator (XT) with PLL (XTPLL)	Primary	01	011	
Primary Oscillator (EC) with PLL (ECPLL)	Primary	00	011	1
Primary Oscillator (HS)	Primary	10	010	
Primary Oscillator (XT)	Primary	01	010	
Primary Oscillator (EC)	Primary	00	010	1
Fast RC Oscillator (FRC) with Divide-by-N and PLL (FRCPLL)	Internal	xx	001	1
Fast RC Oscillator (FRC)	Internal	xx	000	1

Note 1: OSC2 pin function is determined by the OSCIOFNC Configuration bit.

2: This is the default oscillator mode for an unprogrammed (erased) device.

9.2 Oscillator Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note: In the event you are not able to access the product page using the link above, enter this URL in your browser:
<http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464>

9.2.1 KEY RESOURCES

- “**Oscillator**” (DS70580) in the “*dsPIC33/PIC24 Family Reference Manual*”
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related “*dsPIC33/PIC24 Family Reference Manual*” Sections
- Development Tools

10.3 Doze Mode

The preferred strategies for reducing power consumption are changing clock speed and invoking one of the power-saving modes. In some circumstances, this cannot be practical. For example, it may be necessary for an application to maintain uninterrupted synchronous communication, even while it is doing nothing else. Reducing system clock speed can introduce communication errors, while using a power-saving mode can stop communications completely.

Doze mode is a simple and effective alternative method to reduce power consumption while the device is still executing code. In this mode, the system clock continues to operate from the same source and at the same speed. Peripheral modules continue to be clocked at the same speed, while the CPU clock speed is reduced. Synchronization between the two clock domains is maintained, allowing the peripherals to access the SFRs while the CPU executes code at a slower rate.

Doze mode is enabled by setting the DOZEN bit (CLKDIV<11>). The ratio between peripheral and core clock speed is determined by the DOZE<2:0> bits (CLKDIV<14:12>). There are eight possible configurations, from 1:1 to 1:128, with 1:1 being the default setting.

Programs can use Doze mode to selectively reduce power consumption in event-driven applications. This allows clock-sensitive functions, such as synchronous communications, to continue without interruption while the CPU idles, waiting for something to invoke an interrupt routine. An automatic return to full-speed CPU operation on interrupts can be enabled by setting the ROI bit (CLKDIV<15>). By default, interrupt events have no effect on Doze mode operation.

For example, suppose the device is operating at 20 MIPS and the ECAN™ module has been configured for 500 kbps, based on this device operating speed. If the device is placed in Doze mode with a clock frequency ratio of 1:4, the ECAN module continues to communicate at the required bit rate of 500 kbps, but the CPU now starts executing instructions at a frequency of 5 MIPS.

10.4 Peripheral Module Disable

The Peripheral Module Disable (PMD) registers provide a method to disable a peripheral module by stopping all clock sources supplied to that module. When a peripheral is disabled using the appropriate PMD control bit, the peripheral is in a minimum power consumption state. The control and status registers associated with the peripheral are also disabled, so writes to those registers do not have effect and read values are invalid.

A peripheral module is enabled only if both the associated bit in the PMD register is cleared and the peripheral is supported by the specific dsPIC® DSC variant. If the peripheral is present in the device, it is enabled in the PMD register by default.

Note: If a PMD bit is set, the corresponding module is disabled after a delay of one instruction cycle. Similarly, if a PMD bit is cleared, the corresponding module is enabled after a delay of one instruction cycle (assuming the module control registers are already configured to enable module operation).

10.5 Power-Saving Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note: In the event you are not able to access the product page using the link above, enter this URL in your browser:
<http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464>

10.5.1 KEY RESOURCES

- **“Watchdog Timer and Power-Saving Modes”** (DS70615) in the *“dsPIC33/PIC24 Family Reference Manual”*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *“dsPIC33/PIC24 Family Reference Manual”* Sections
- Development Tools

12.0 TIMER1

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to “Timers” (DS70362) in the “dsPIC33/PIC24 Family Reference Manual”, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 “Memory Organization”** in this data sheet for device-specific register and bit information.

The Timer1 module is a 16-bit timer that can operate as a free-running interval timer/counter.

The Timer1 module has the following unique features over other timers:

- Can be operated in Asynchronous Counter mode from an external clock source
- The external clock input (T1CK) can optionally be synchronized to the internal device clock and the clock synchronization is performed after the prescaler

A block diagram of Timer1 is shown in Figure 12-1.

The Timer1 module can operate in one of the following modes:

- Timer mode
- Gated Timer mode
- Synchronous Counter mode
- Asynchronous Counter mode

In Timer and Gated Timer modes, the input clock is derived from the internal instruction cycle clock (Fcy). In Synchronous and Asynchronous Counter modes, the input clock is derived from the external clock input at the T1CK pin.

The Timer modes are determined by the following bits:

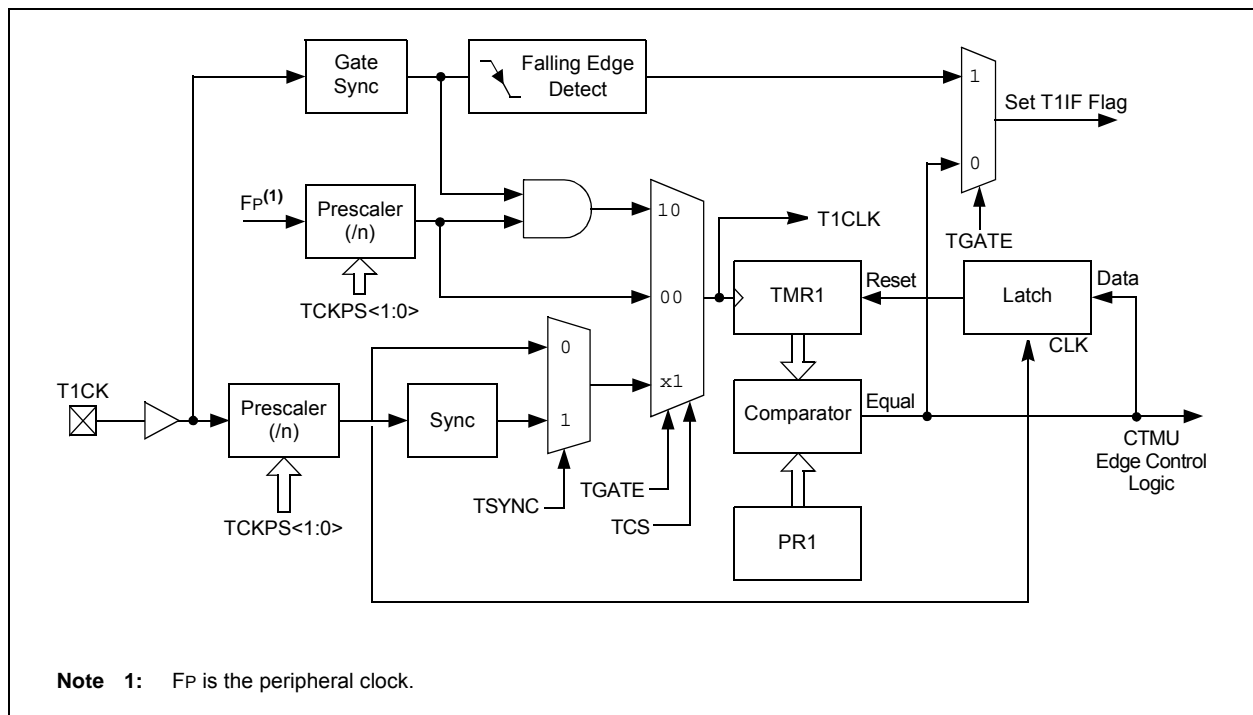
- Timer Clock Source Control bit (TCS): T1CON<1>
- Timer Synchronization Control bit (TSYNC): T1CON<2>
- Timer Gate Control bit (TGATE): T1CON<6>

Timer control bit setting for different operating modes are given in the Table 12-1.

TABLE 12-1: TIMER MODE SETTINGS

Mode	TCS	TGATE	TSYNC
Timer	0	0	x
Gated Timer	0	1	x
Synchronous Counter	1	x	1
Asynchronous Counter	1	x	0

FIGURE 12-1: 16-BIT TIMER1 MODULE BLOCK DIAGRAM



14.0 INPUT CAPTURE

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to “**Input Capture**” (DS70352) in the “*dsPIC33/dsPIC24 Family Reference Manual*”, which is available from the Microchip web site (www.microchip.com).

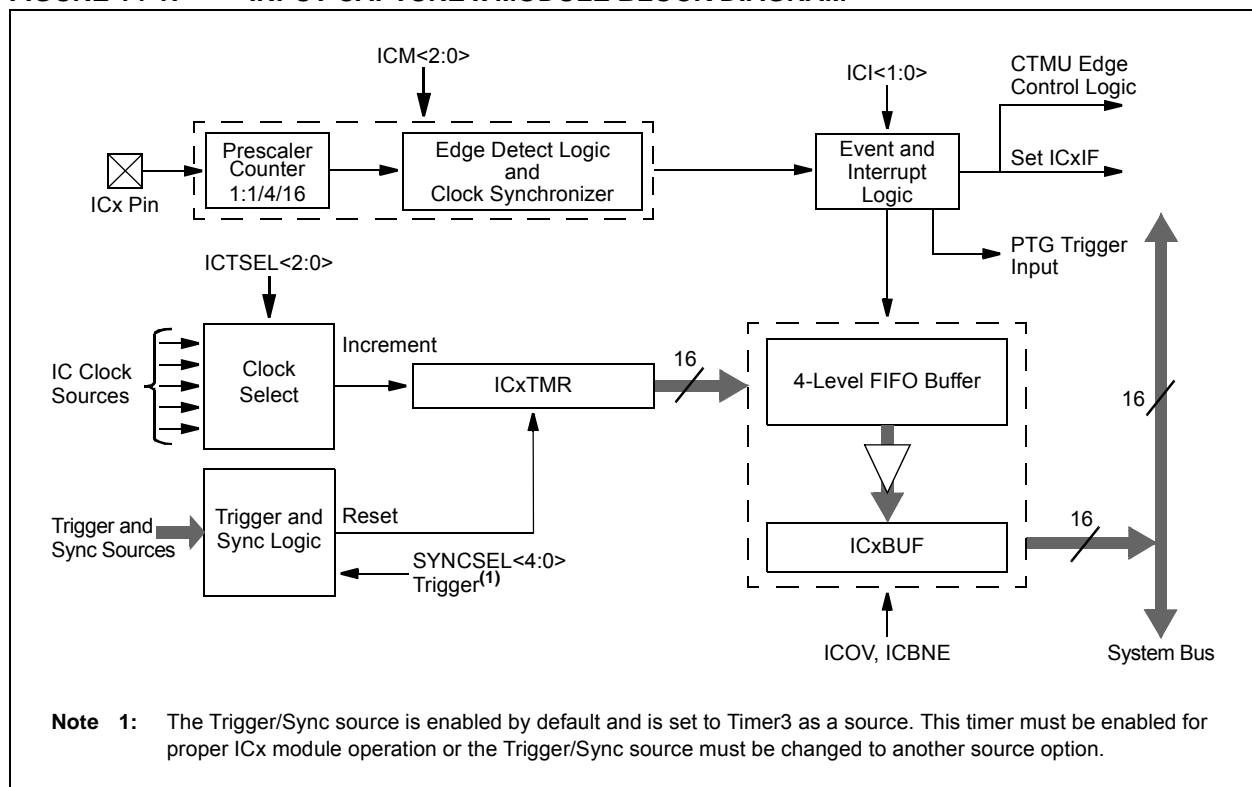
2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 “Memory Organization”** in this data sheet for device-specific register and bit information.

The input capture module is useful in applications requiring frequency (period) and pulse measurement. The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices support four input capture channels.

Key features of the input capture module include:

- Hardware-configurable for 32-bit operation in all modes by cascading two adjacent modules
- Synchronous and Trigger modes of output compare operation, with up to 19 user-selectable Trigger/Sync sources available
- A 4-level FIFO buffer for capturing and holding timer values for several events
- Configurable interrupt generation
- Up to six clock sources available for each module, driving a separate internal 16-bit counter

FIGURE 14-1: INPUT CAPTURE x MODULE BLOCK DIAGRAM



REGISTER 16-15: FCLCONx: PWMx FAULT CURRENT-LIMIT CONTROL REGISTER⁽¹⁾

- bit 7-3 **FLTSRC<4:0>**: Fault Control Signal Source Select for PWM Generator # bits
- 11111 = Fault 32 (**default**)
 - 11110 = Reserved
 - .
 - .
 - .
 - 01100 = Reserved
 - 01011 = Comparator 4
 - 01010 = Op Amp/Comparator 3
 - 01001 = Op Amp/Comparator 2
 - 01000 = Op Amp/Comparator 1
 - 00111 = Reserved
 - 00110 = Reserved
 - 00101 = Reserved
 - 00100 = Reserved
 - 00011 = Fault 4
 - 00010 = Fault 3
 - 00001 = Fault 2
 - 00000 = Fault 1
- bit 2 **FLTPOL**: Fault Polarity for PWM Generator # bit⁽²⁾
- 1 = The selected Fault source is active-low
 - 0 = The selected Fault source is active-high
- bit 1-0 **FLTMOD<1:0>**: Fault Mode for PWM Generator # bits
- 11 = Fault input is disabled
 - 10 = Reserved
 - 01 = The selected Fault source forces PWMxH, PWMxL pins to FLTDAT values (cycle)
 - 00 = The selected Fault source forces PWMxH, PWMxL pins to FLTDAT values (latched condition)

- Note 1:** If the PWMLOCK Configuration bit (FOSCSEL<6>) is a '1', the IOCONx register can only be written after the unlock sequence has been executed.
- 2:** These bits should be changed only when PTEN = 0. Changing the clock selection during operation will yield unpredictable results.

18.3 SPIx Control Registers

REGISTER 18-1: SPIxSTAT: SPIx STATUS AND CONTROL REGISTER

R/W-0	U-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0
SPIEN	—	SPISIDL	—	—	SPIBEC<2:0>		
bit 15							bit 8

R/W-0	R/C-0, HS	R/W-0	R/W-0	R/W-0	R/W-0	R-0, HS, HC	R-0, HS, HC
SRMPT	SPIROV	SRXMPT	SISEL2	SISEL1	SISEL0	SPITBF	SPIRBF
bit 7							bit 0

Legend:	C = Clearable bit	HS = Hardware Settable bit	HC = Hardware Clearable bit
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

- bit 15 **SPIEN:** SPIx Enable bit
1 = Enables the module and configures SCKx, SDOx, SDIx and \overline{SSx} as serial port pins
0 = Disables the module
- bit 14 **Unimplemented:** Read as '0'
- bit 13 **SPISIDL:** SPIx Stop in Idle Mode bit
1 = Discontinues the module operation when device enters Idle mode
0 = Continues the module operation in Idle mode
- bit 12-11 **Unimplemented:** Read as '0'
- bit 10-8 **SPIBEC<2:0>:** SPIx Buffer Element Count bits (valid in Enhanced Buffer mode)
Master mode:
Number of SPIx transfers that are pending.
Slave mode:
Number of SPIx transfers that are unread.
- bit 7 **SRMPT:** SPIx Shift Register (SPIxSR) Empty bit (valid in Enhanced Buffer mode)
1 = SPIx Shift register is empty and Ready-To-Send or receive the data
0 = SPIx Shift register is not empty
- bit 6 **SPIROV:** SPIx Receive Overflow Flag bit
1 = A new byte/word is completely received and discarded; the user application has not read the previous data in the SPIxBUF register
0 = No overflow has occurred
- bit 5 **SRXMPT:** SPIx Receive FIFO Empty bit (valid in Enhanced Buffer mode)
1 = RX FIFO is empty
0 = RX FIFO is not empty
- bit 4-2 **SISEL<2:0>:** SPIx Buffer Interrupt Mode bits (valid in Enhanced Buffer mode)
111 = Interrupt when the SPIx transmit buffer is full (SPITBF bit is set)
110 = Interrupt when last bit is shifted into SPIxSR and as a result, the TX FIFO is empty
101 = Interrupt when the last bit is shifted out of SPIxSR and the transmit is complete
100 = Interrupt when one data is shifted into the SPIxSR and as a result, the TX FIFO has one open memory location
011 = Interrupt when the SPIx receive buffer is full (SPIRBF bit is set)
010 = Interrupt when the SPIx receive buffer is 3/4 or more full
001 = Interrupt when data is available in the receive buffer (SRMPT bit is set)
000 = Interrupt when the last data in the receive buffer is read and as a result, the buffer is empty (SRXMPT bit is set)

TABLE 27-2: CONFIGURATION BITS DESCRIPTION

Bit Field	Description
GCP	General Segment Code-Protect bit 1 = User program memory is not code-protected 0 = Code protection is enabled for the entire program memory space
GWRP	General Segment Write-Protect bit 1 = User program memory is not write-protected 0 = User program memory is write-protected
IESO	Two-Speed Oscillator Start-up Enable bit 1 = Start up device with FRC, then automatically switch to the user-selected oscillator source when ready 0 = Start up device with user-selected oscillator source
PWMLOCK ⁽¹⁾	PWM Lock Enable bit 1 = Certain PWM registers may only be written after a key sequence 0 = PWM registers may be written without a key sequence
FNOSC<2:0>	Oscillator Selection bits 111 = Fast RC Oscillator with Divide-by-N (FRCDIVN) 110 = Fast RC Oscillator with Divide-by-16 (FRCDIV16) 101 = Low-Power RC Oscillator (LPRC) 100 = Reserved; do not use 011 = Primary Oscillator with PLL module (XT + PLL, HS + PLL, EC + PLL) 010 = Primary Oscillator (XT, HS, EC) 001 = Fast RC Oscillator with Divide-by-N with PLL module (FRCPLL) 000 = Fast RC Oscillator (FRC)
FCKSM<1:0>	Clock Switching Mode bits 1x = Clock switching is disabled, Fail-Safe Clock Monitor is disabled 01 = Clock switching is enabled, Fail-Safe Clock Monitor is disabled 00 = Clock switching is enabled, Fail-Safe Clock Monitor is enabled
IOL1WAY	Peripheral Pin Select Configuration bit 1 = Allow only one reconfiguration 0 = Allow multiple reconfigurations
OSCIOFNC	OSC2 Pin Function bit (except in XT and HS modes) 1 = OSC2 is the clock output 0 = OSC2 is a general purpose digital I/O pin
POSCMD<1:0>	Primary Oscillator Mode Select bits 11 = Primary Oscillator is disabled 10 = HS Crystal Oscillator mode 01 = XT Crystal Oscillator mode 00 = EC (External Clock) mode
FWDTEN	Watchdog Timer Enable bit 1 = Watchdog Timer is always enabled (LPRC oscillator cannot be disabled. Clearing the SWDTEN bit in the RCON register will have no effect.) 0 = Watchdog Timer is enabled/disabled by user software (LPRC can be disabled by clearing the SWDTEN bit in the RCON register)
WINDIS	Watchdog Timer Window Enable bit 1 = Watchdog Timer in Non-Window mode 0 = Watchdog Timer in Window mode
PLLKEN	PLL Lock Enable bit 1 = PLL lock is enabled 0 = PLL lock is disabled

Note 1: This bit is only available on dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices.

2: When JTAGEN = 1, an internal pull-up resistor is enabled on the TMS pin. Erased devices default to JTAGEN = 1. Applications requiring I/O pins in a high-impedance state (tri-state) in Reset should use pins other than TMS for this purpose.

TABLE 28-1: SYMBOLS USED IN OPCODE DESCRIPTIONS (CONTINUED)

Field	Description
Wm,Wn	Dividend, Divisor working register pair (direct addressing)
Wm*Wm	Multiplicand and Multiplier working register pair for Square instructions $\in \{W4 * W4, W5 * W5, W6 * W6, W7 * W7\}$
Wm*Wn	Multiplicand and Multiplier working register pair for DSP instructions $\in \{W4 * W5, W4 * W6, W4 * W7, W5 * W6, W5 * W7, W6 * W7\}$
Wn	One of 16 working registers $\in \{W0...W15\}$
Wnd	One of 16 destination working registers $\in \{W0...W15\}$
Wns	One of 16 source working registers $\in \{W0...W15\}$
WREG	W0 (working register used in file register instructions)
Ws	Source W register $\in \{Ws, [Ws], [Ws++] , [Ws--], [++Ws], [--Ws] \}$
Wso	Source W register $\in \{Wns, [Wns], [Wns++] , [Wns--], [++Wns], [--Wns], [Wns+Wb] \}$
Wx	X Data Space Prefetch Address register for DSP instructions $\in \{[W8] + = 6, [W8] + = 4, [W8] + = 2, [W8], [W8] - = 6, [W8] - = 4, [W8] - = 2, [W9] + = 6, [W9] + = 4, [W9] + = 2, [W9], [W9] - = 6, [W9] - = 4, [W9] - = 2, [W9 + W12], \text{none}\}$
Wxd	X Data Space Prefetch Destination register for DSP instructions $\in \{W4...W7\}$
Wy	Y Data Space Prefetch Address register for DSP instructions $\in \{[W10] + = 6, [W10] + = 4, [W10] + = 2, [W10], [W10] - = 6, [W10] - = 4, [W10] - = 2, [W11] + = 6, [W11] + = 4, [W11] + = 2, [W11], [W11] - = 6, [W11] - = 4, [W11] - = 2, [W11 + W12], \text{none}\}$
Wyd	Y Data Space Prefetch Destination register for DSP instructions $\in \{W4...W7\}$

TABLE 30-8: DC CHARACTERISTICS: POWER-DOWN CURRENT (IPD)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended	
Parameter No.	Typ.	Max.	Units	Conditions
Power-Down Current (IPD)⁽¹⁾ – dsPIC33EP32GP50X, dsPIC33EP32MC20X/50X and PIC24EP32GP/MC20X				
DC60d	30	100	μA	-40°C
DC60a	35	100	μA	+25°C
DC60b	150	200	μA	+85°C
DC60c	250	500	μA	+125°C
Power-Down Current (IPD)⁽¹⁾ – dsPIC33EP64GP50X, dsPIC33EP64MC20X/50X and PIC24EP64GP/MC20X				
DC60d	25	100	μA	-40°C
DC60a	30	100	μA	+25°C
DC60b	150	350	μA	+85°C
DC60c	350	800	μA	+125°C
Power-Down Current (IPD)⁽¹⁾ – dsPIC33EP128GP50X, dsPIC33EP128MC20X/50X and PIC24EP128GP/MC20X				
DC60d	30	100	μA	-40°C
DC60a	35	100	μA	+25°C
DC60b	150	350	μA	+85°C
DC60c	550	1000	μA	+125°C
Power-Down Current (IPD)⁽¹⁾ – dsPIC33EP256GP50X, dsPIC33EP256MC20X/50X and PIC24EP256GP/MC20X				
DC60d	35	100	μA	-40°C
DC60a	40	100	μA	+25°C
DC60b	250	450	μA	+85°C
DC60c	1000	1200	μA	+125°C
Power-Down Current (IPD)⁽¹⁾ – dsPIC33EP512GP50X, dsPIC33EP512MC20X/50X and PIC24EP512GP/MC20X				
DC60d	40	100	μA	-40°C
DC60a	45	100	μA	+25°C
DC60b	350	800	μA	+85°C
DC60c	1100	1500	μA	+125°C

Note 1: IPD (Sleep) current is measured as follows:

- CPU core is off, oscillator is configured in EC mode and external clock is active; OSC1 is driven with external square wave from rail-to-rail (EC clock overshoot/undershoot < 250 mV required)
- CLKO is configured as an I/O input pin in the Configuration Word
- All I/O pins are configured as inputs and pulled to VSS
- MCLR = VDD, WDT and FSCM are disabled
- All peripheral modules are disabled (PMDx bits are all set)
- The VREGS bit (RCON<8>) = 0 (i.e., core regulator is set to standby while the device is in Sleep mode)
- The VREGSF bit (RCON<11>) = 0 (i.e., Flash regulator is set to standby while the device is in Sleep mode)
- JTAG is disabled

TABLE 30-56: CTMU CURRENT SOURCE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for Extended				
Param No.	Symbol	Characteristic	Min.	Typ.	Max.	Units	Conditions
CTMU Current Source							
CTMUI1	IOUT1	Base Range ⁽¹⁾	0.29	—	0.77	μA	CTMUICON<9:8> = 01
CTMUI2	IOUT2	10x Range ⁽¹⁾	3.85	—	7.7	μA	CTMUICON<9:8> = 10
CTMUI3	IOUT3	100x Range ⁽¹⁾	38.5	—	77	μA	CTMUICON<9:8> = 11
CTMUI4	IOUT4	1000x Range ⁽¹⁾	385	—	770	μA	CTMUICON<9:8> = 00
CTMUFV1	VF	Temperature Diode Forward Voltage ^(1,2)	—	0.598	—	V	$T_A = +25^{\circ}\text{C}$, CTMUICON<9:8> = 01
			—	0.658	—	V	$T_A = +25^{\circ}\text{C}$, CTMUICON<9:8> = 10
			—	0.721	—	V	$T_A = +25^{\circ}\text{C}$, CTMUICON<9:8> = 11
CTMUFV2	VFVR	Temperature Diode Rate of Change ^(1,2,3)	—	-1.92	—	$\text{mV}/^{\circ}\text{C}$	CTMUICON<9:8> = 01
			—	-1.74	—	$\text{mV}/^{\circ}\text{C}$	CTMUICON<9:8> = 10
			—	-1.56	—	$\text{mV}/^{\circ}\text{C}$	CTMUICON<9:8> = 11

Note 1: Nominal value at center point of current trim range (CTMUICON<15:10> = 000000).

2: Parameters are characterized but not tested in manufacturing.

3: Measurements taken with the following conditions:

- $V_{\text{REF+}} = A_{\text{VDD}} = 3.3\text{V}$
- ADC configured for 10-bit mode
- ADC module configured for conversion speed of 500 ksp/s
- All PMDx bits are cleared (PMDx = 0)
- Executing a `while(1)` statement
- Device operating from the FRC with no PLL

TABLE 30-61: ADC CONVERSION (10-BIT MODE) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) ⁽¹⁾ Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	Symbol	Characteristic	Min.	Typ.	Max.	Units	Conditions
Clock Parameters							
AD50	TAD	ADC Clock Period	76	—	—	ns	
AD51	tRC	ADC Internal RC Oscillator Period ⁽²⁾	—	250	—	ns	
Conversion Rate							
AD55	tCONV	Conversion Time	—	12 TAD	—	—	
AD56	FCNV	Throughput Rate	—	—	1.1	Msp/s	Using simultaneous sampling
AD57a	TSAMP	Sample Time when Sampling any ANx Input	2 TAD	—	—	—	
AD57b	TSAMP	Sample Time when Sampling the Op Amp Outputs (Configuration A and Configuration B) ^(4,5)	4 TAD	—	—	—	
Timing Parameters							
AD60	tPCS	Conversion Start from Sample Trigger ^(2,3)	2 TAD	—	3 TAD	—	Auto-convert trigger is not selected
AD61	tPSS	Sample Start from Setting Sample (SAMP) bit ^(2,3)	2 TAD	—	3 TAD	—	
AD62	tCSS	Conversion Completion to Sample Start (ASAM = 1) ^(2,3)	—	0.5 TAD	—	—	
AD63	tDPU	Time to Stabilize Analog Stage from ADC Off to ADC On ^(2,3)	—	—	20	μs	(Note 6)

Note 1: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules (ADC, op amp/comparator and comparator voltage reference) may have degraded performance. Refer to Parameter BO10 in Table 30-13 for the minimum and maximum BOR values.

2: Parameters are characterized but not tested in manufacturing.

3: Because the sample caps will eventually lose charge, clock rates below 10 kHz may affect linearity performance, especially at elevated temperatures.

4: See Figure 25-6 for configuration information.

5: See Figure 25-7 for configuration information.

6: The parameter, tDPU, is the time required for the ADC module to stabilize at the appropriate level when the module is turned on (ADON (AD1CON1<15>) = 1). During this time, the ADC result is indeterminate.

TABLE 30-62: DMA MODULE TIMING REQUIREMENTS

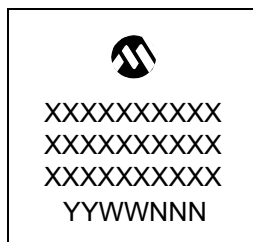
AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	Characteristic	Min.	Typ. ⁽¹⁾	Max.	Units	Conditions
DM1	DMA Byte/Word Transfer Latency	1 Tcy ⁽²⁾	—	—	ns	

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Because DMA transfers use the CPU data bus, this time is dependent on other functions on the bus.

33.1 Package Marking Information (Continued)

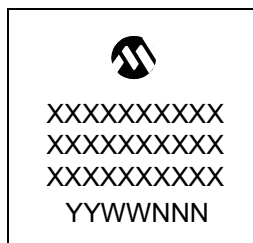
36-Lead VTLA (TLA)



Example



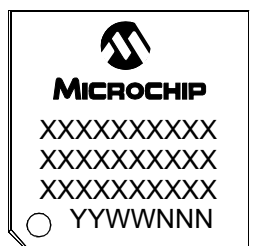
44-Lead VTLA (TLA)



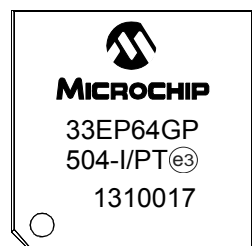
Example



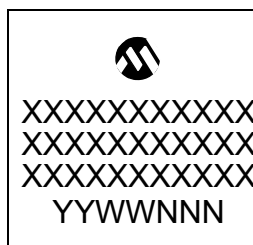
44-Lead TQFP



Example



44-Lead QFN (8x8x0.9 mm)

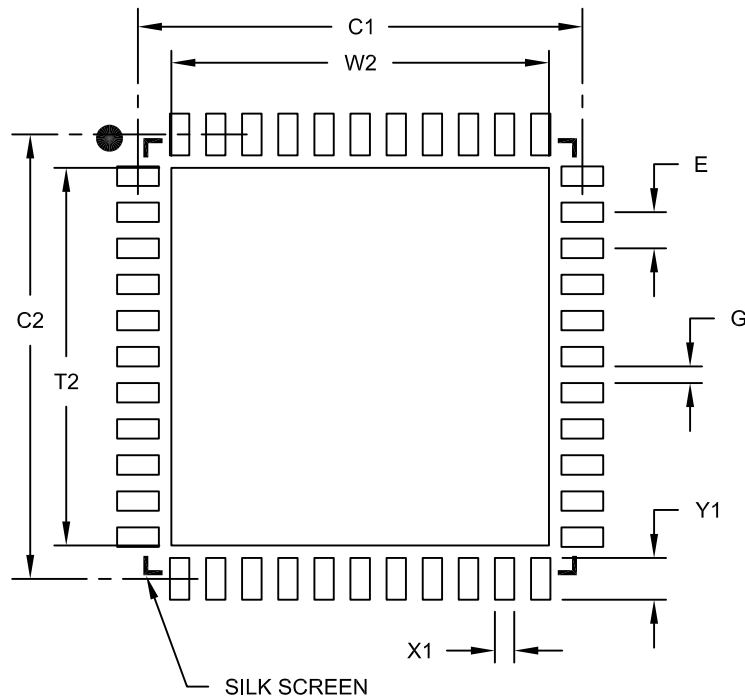


Example



44-Lead Plastic Quad Flat, No Lead Package (ML) - 8x8 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Optional Center Pad Width	W2			6.60
Optional Center Pad Length	T2			6.60
Contact Pad Spacing	C1		8.00	
Contact Pad Spacing	C2		8.00	
Contact Pad Width (X44)	X1			0.35
Contact Pad Length (X44)	Y1			0.85
Distance Between Pads	G	0.25		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2103B